AMENDMENTS TO THE CLAIMS:

Claim 1 (previously presented): A method of surface-mounting a plurality of electronic components having conductive connecting members, said method comprising the steps of:

providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas being no greater than corresponding one of said electronic components and including at least one terminal part therein, at least one of said terminal-forming areas including a plurality of terminal parts directly thereon such that each pair of said terminal parts within any one of said terminal-forming areas is closer to each other than any pair of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.

Claim 2 (original): The method of claim 1 wherein said anisotropic conductive layer is formed by attaching a single sheet of anisotropic conductive film to said target surface, said anisotropic conductive film containing conductive particles dispersed inside a thermosetting synthetic resin.

Claim 3 (withdrawn): The method of claim 1 wherein said anisotropic conductive layer is formed by applying an anisotropic conductive adhesive to said target surface, said anisotropic conductive adhesive containing conductive particles dispersed inside a thermosetting synthetic resin.

Claim 4 (original): The method of claim 2 wherein said anisotropic conductive layer is heated as said plurality of electronic components are pressed to said anisotropic conductive layer.

Claim 5 (withdrawn): The method of claim 3 wherein said anisotropic conductive layer is heated as said plurality of electronic components are pressed to said anisotropic conductive layer.

Claim 6 (original): The method of claim 2 further comprising the step of preparing said single sheet of anisotropic conductive film in a shape according to positions and shapes of said terminal-forming areas of said target surface.

Claim 7 (original): The method of claim 4 further comprising the step of preparing said single sheet of anisotropic conductive film in a shape according to positions and shapes of said terminal-forming areas of said target surface.

Claim 8 (withdrawn): A surface-mounted structure comprising:

a circuit board with a surface having thereon a plurality of terminal-forming areas each containing terminal parts therein;

a plurality of electronic components having conductive connecting members thereon; and

an anisotropic conductive layer between and attached to both said surface of said circuit board and said plurality of electronic components, said anisotropic conductive layer being thermally hardened, electrically conductive individually between said terminal parts and corresponding ones of said conductive connecting members of said plurality of electronic components, and being electrically insulative elsewhere.

Claim 9 (withdrawn): The surface-mounted structure of claim 8 wherein said anisotropic conductive layer comprises conductive particles dispersed inside a thermosetting synthetic resin.

Claim 10 (new): A method of surface-mounting a plurality of electronic components having conductive connecting members, said method comprising the steps of:

providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas being no greater than corresponding one of said electronic components and including at least one terminal part therein, at least one of said terminal-forming areas including a plurality of terminal parts directly thereon such that each pair of said terminal parts within any one of said terminal-forming areas is closer to each other than any pair of said terminal parts in different ones of said terminal-forming areas, wherein the terminal parts are distributed in a non-uniform manner depending on the sizes of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.

Claim 11 (new): The method of claim 10 wherein said anisotropic conductive layer is formed by attaching a single sheet of anisotropic conductive film to said target surface, said anisotropic conductive film containing conductive particles dispersed inside a thermosetting synthetic resin.

Claim 12 (new): The method of claim 11 wherein said anisotropic conductive layer is heated as said plurality of electronic components are pressed to said anisotropic conductive layer.

Claim 13 (new): The method of claim 11 further comprising the step of preparing said single sheet of anisotropic conductive film in a shape according to positions and shapes of said terminal-forming areas of said target surface.

Claim 14 (new): The method of claim 12 further comprising the step of preparing said single sheet of anisotropic conductive film in a shape according to positions and shapes of said terminal-forming areas of said target surface.

Claims concluded